



Board Characteristics - 6 LAYER BOARD

1. $T_g > 170C$
2. Minimum trace width: 0.005" and clearance: 0.005"
4. 1 oz copper for all layers
5. Electroless Nickel Immersion Gold plating, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
6. Board Thickness: 0.093 +/- 0.008
7. FHS tolerances: +/- 0.003 unless specified otherwise.
8. $Z_c=50 \text{ Ohm}$, $Z_d=100 \text{ Ohm}$ Controlled Impedance
9. Apply Solder Mask over bare copper.
10. Remove all non-functional inner layer pads for pins and vias.
11. Do not increase size of thermal pads and associated spoke connections on holes.

BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.0091	443	YES	---	
⊞	.039370079	4	NO	---	
⊕	.041	97	YES	---	
⊞	.052	83	YES	---	
⊖	.057	26	YES	---	
⊞	.066	18	YES	---	
⊕	.11811024	4	NO	---	
□	.12	8	YES	---	
	.12795	6	YES	---	
	.15	2	NO	---	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XX .XXX DO NOT SCALE DRAWING		CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP		
TREATMENT		APPROVALS	DATE	TITLE DAMIC - OBDB Specification Drawing		
FINISH		DRAWN M. Bogdan	3/4/2021	SIZE B	FSCM NO.	REV. A
SIMILAR TO		CHECKED M. Bogdan	3/4/2021	DWG. NO. 2986	SHEET	
ACT. WT	CALC. WT	ISSUED		SCALE 1/2	SHEET	